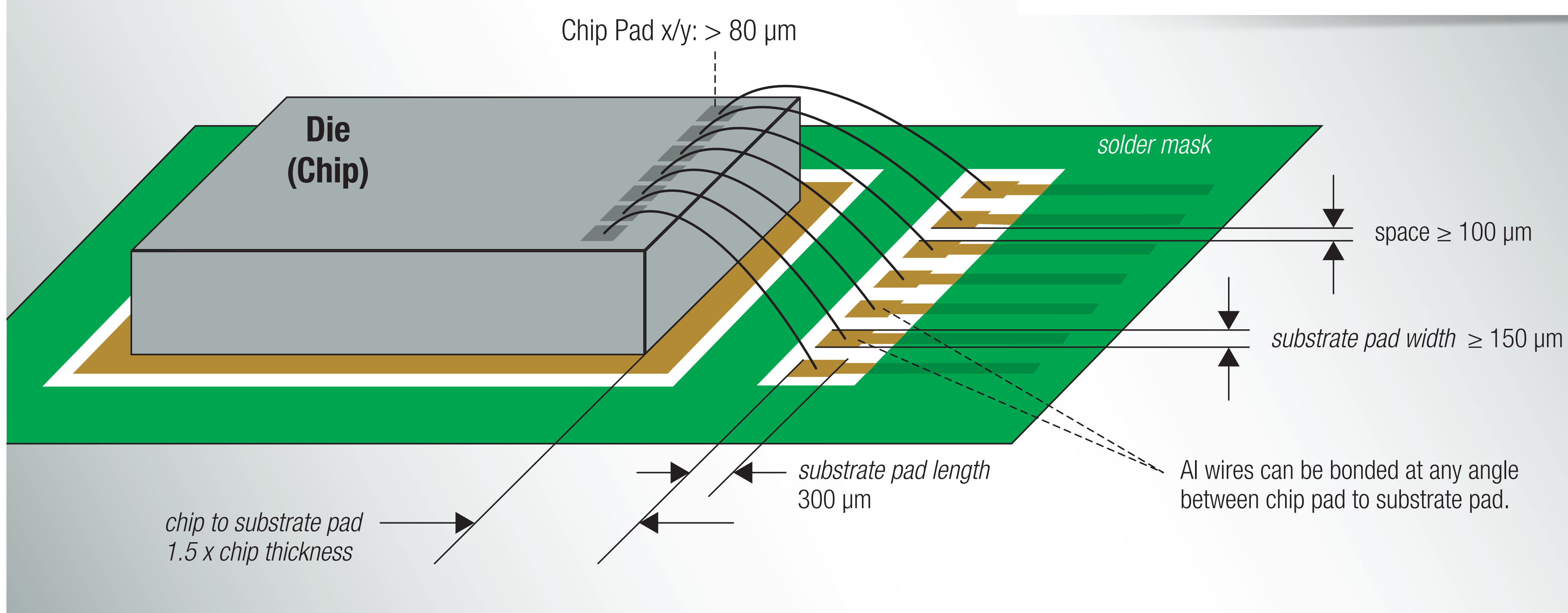
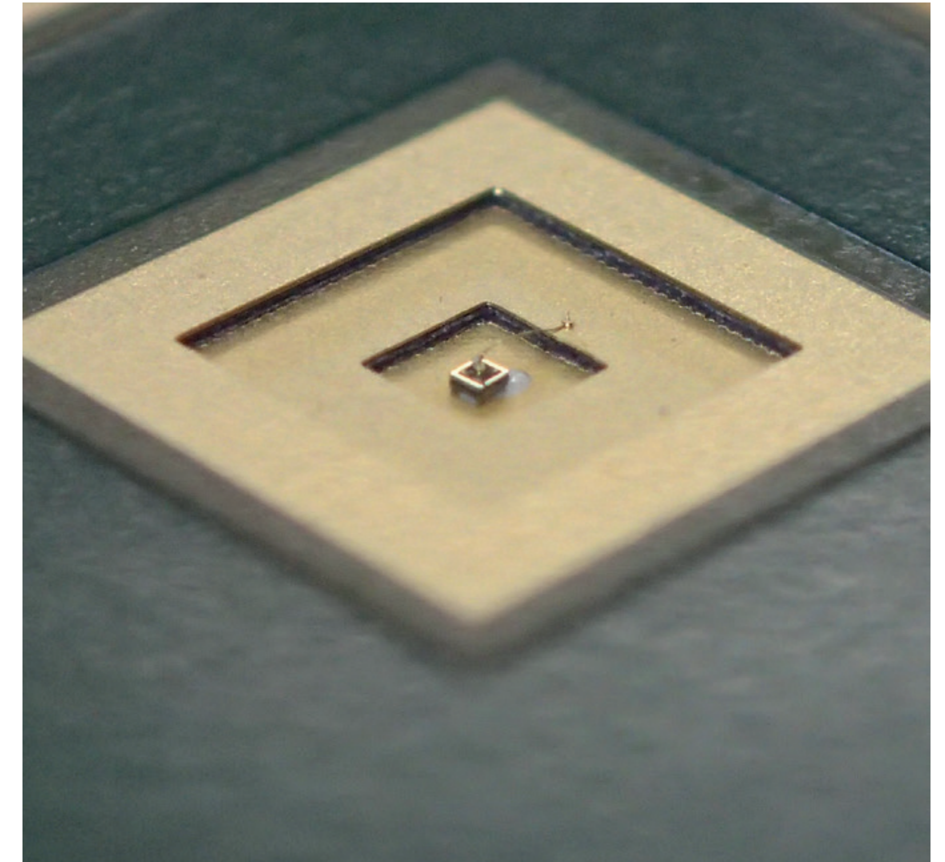
Chip on board / Wire Bonding Design Guide

Design Rules for Aluminium (Al) wire bonding

! Chip pad to substrate pad orientation is parallel.

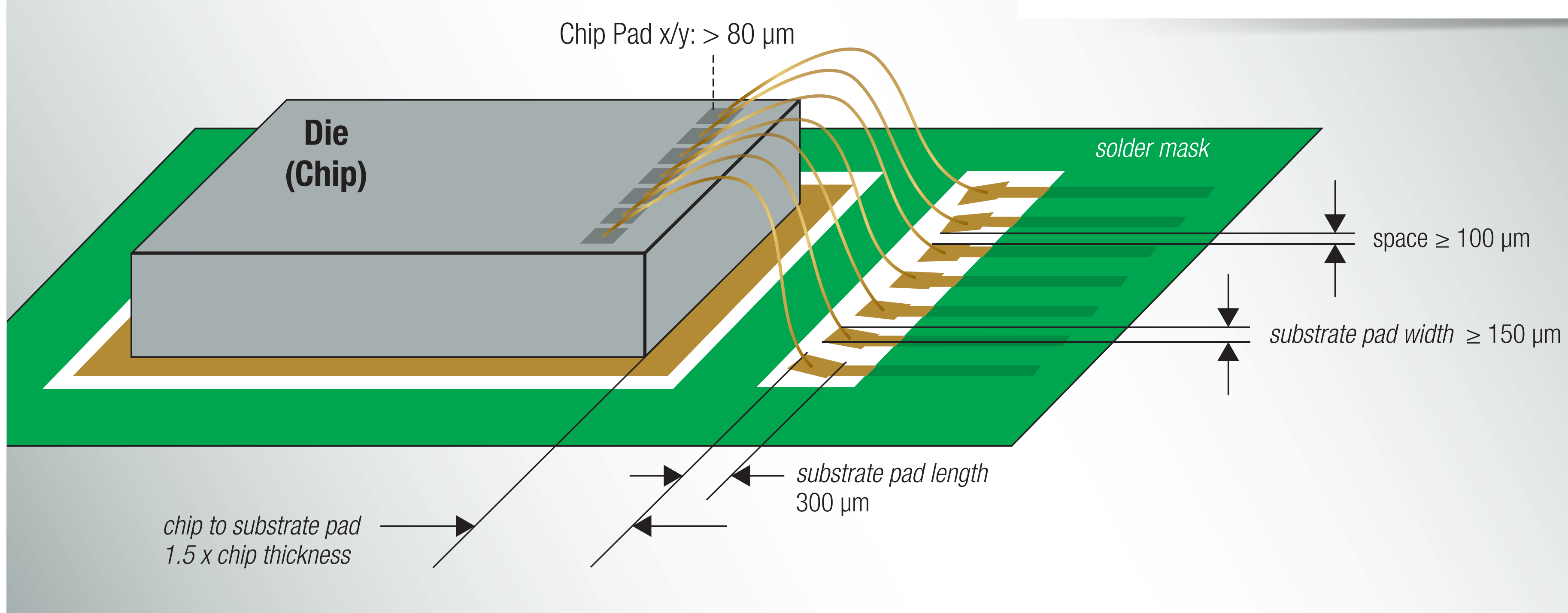


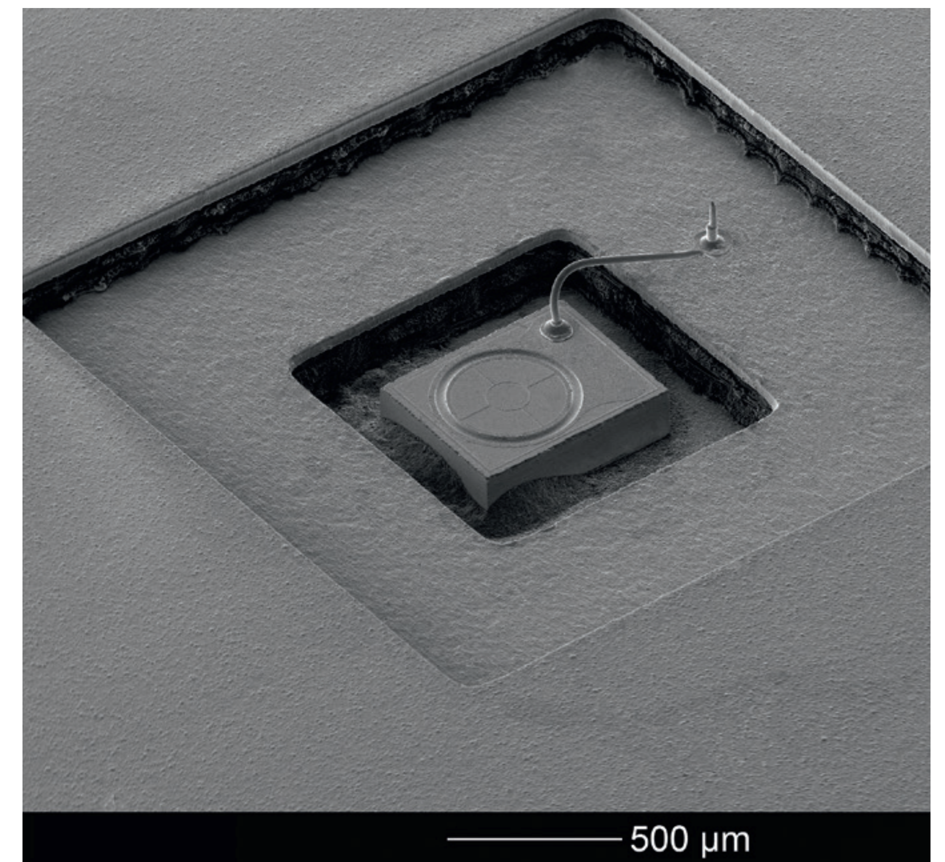


Wire bonded diode in a multi-step Lasercavity

Design Rules for Gold (Au) wire bonding

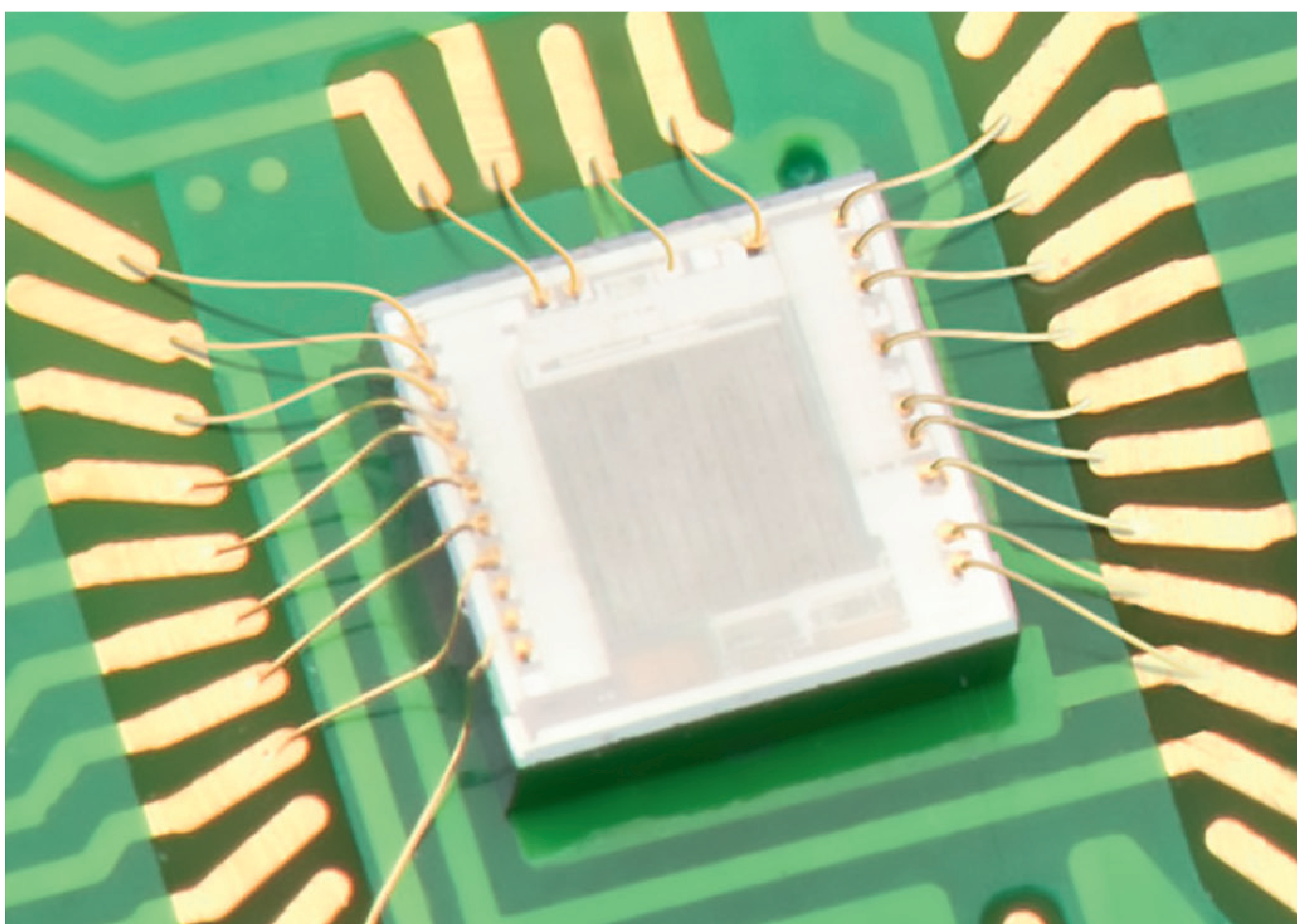
! Chip pad to substrate pad must be aligned in the same direction.





REM magnification of a wire bonded diode in a multi-step Lasercavity

! The solder mask must be released as block in the area of the bond pads



Example of an optimal orientation of the bonding pads to the wire bonds